



## DFN6L-2\*2 物料成分表

### Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition	CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English		
Die	0.80	Si	7440-21-3	100.00%
Lead Frame	3.51	Copper(Cu)	7440-50-8	balance
		Iron(Fe)	7439-89-6	2.1-2.6
		Lead(Pb)	7439-92-1	0.01Max
		Phosphorus(P)	7723-14-0	0.015~0.150
		Zinc(Zn)	7440-66-6	0.050~0.200
		Silver(Ag)	7440-22-4	5.0Max
Epoxy	0.082	Silver	7440-22-4	60-100
		Epoxy Resin.	-	10-30%
		1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	5-10%
		Aromatic polyamine Proprietary	-	1-5%
Wire	0.05	Copper	231-159-6	≥99.99
		Silver	231-131-3	<20ppm
		other	-	-
Mold Compound	5.518	Epoxy Resin A	Trade Secret	1-5%
		Epoxy Resin B	Trade Secret	1-5%
		Phenol Resin	Trade Secret	1-5%
		Silica(Amorphous)A	60676-86-0	70-90%
		Silica(Amorphous)B	7631-86-9	1-5%
		Carbon Black	1333-86-4	0.1-1%
Plating	0.041	Sn	7440-31-5	99.99%
Total	10			

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.